IC DIE POWER CONNECTION USING CANTED COIL SPRING

Abstract

A semiconductor device assembly (10) according to the present invention may comprise a semiconductor die (12) having at least one contact pad (14) thereon and a package substrate (16) having at least one lead pad (20) thereon. The package substrate (16) is sized to receive the semiconductor die (12) so that the contact pad (14) on the semiconductor die (12) is substantially aligned with the lead pad (20) on the package substrate (16) when the semiconductor die (12) is positioned on the package substrate (16). A coil spring (22) is positioned between the contact pad (14) on the semiconductor die (12) and the lead pad (20) on the package substrate (16) so that the axis (30) of the coil spring (22) is substantially parallel to the contact pad (14) contained on the semiconductor die (12) and the lead pad (20) contained on the package substrate (16).

Figure 1